

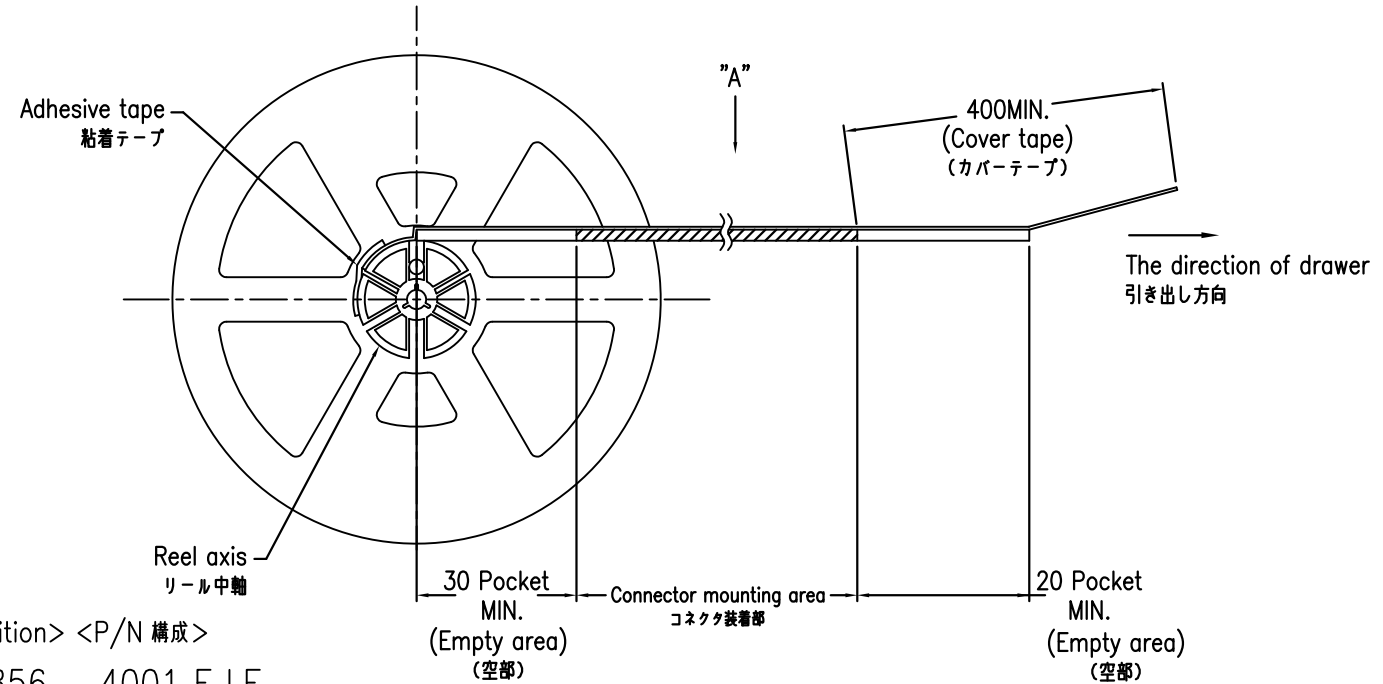
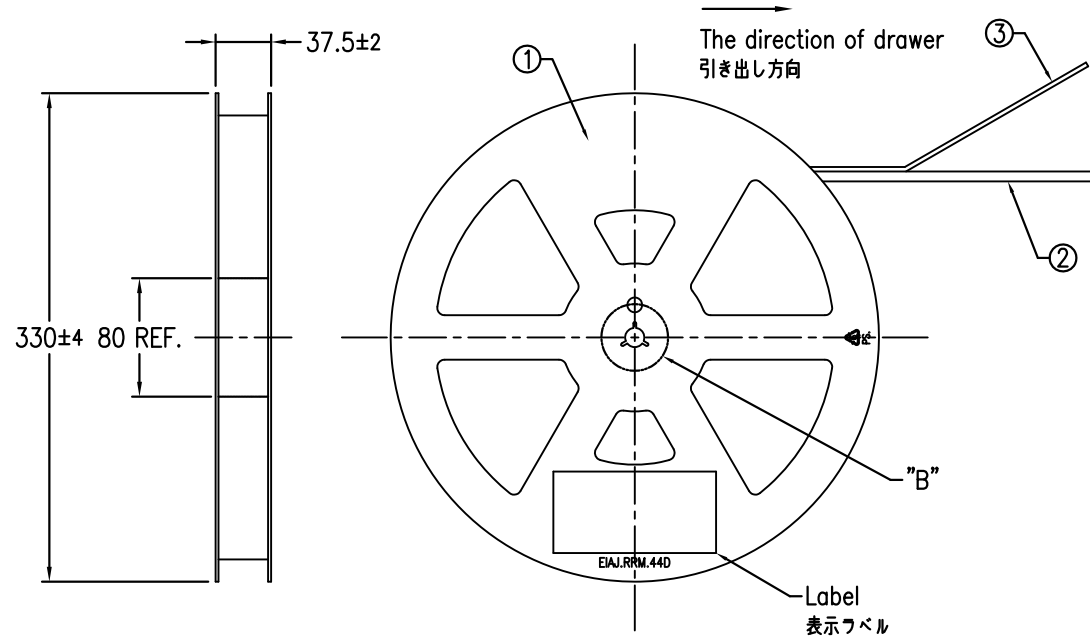
PRODUCT NO.

~~10042856-4001E~~

10042856-4001ELF

PARTS TABLE 部品表

No.	Part name 部品名	Material 材質	QTY.	Note 備考
①	The reel for packaging 梱包用リール	Polystyrene ポリスチレン	1	Color : White, Electrification prevention processing 色:白、帯電防止処理品
②	Emboss tape エンボステープ	PS	1	Electrification prevention processing 帯電防止処理品
③	Cover tape カバーテープ	Polyester ポリエステル	1	
④	Connector コネクタ	See sheet 1	1000	



<P/N composition> <P/N 構成>

△ 10042856 - 4001 E L F

LF : Lead-Free  
LF : 鉛フリー対応品

Packaging form (E : Plastic reel・Embossing tape package)  
梱包形態 (E : プラスチックリール・エンボステープ梱包)

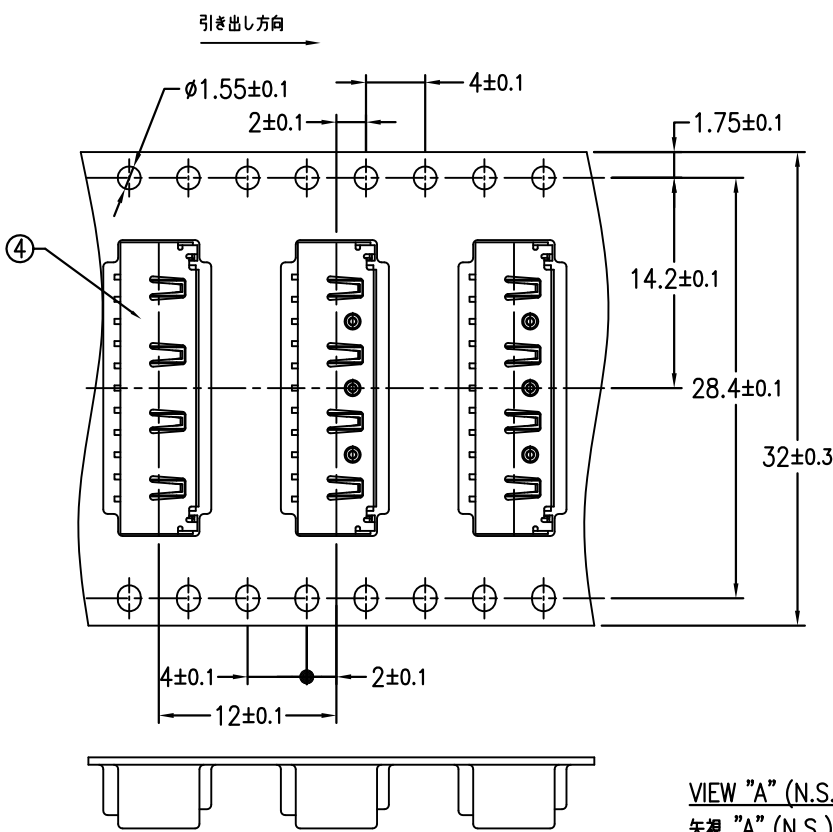
Refer to connector drawing (Sheet 1).  
コネクタ図面参照 (Sheet 1)

NOTE

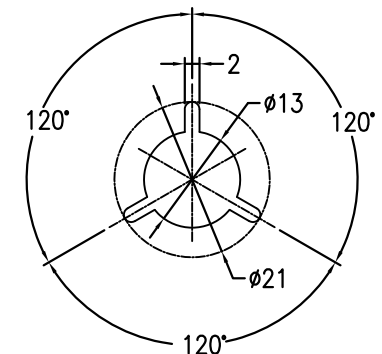
- This article carries out the emboss tape package of the Micro Channel Connector Board Conn.
- The shape and dimension of this article are based on JIS C 0806.  
(Taping of electronic parts (Surface mounted device))

注記

- 本品は マイクロチャンネルコネクタ・ボードコネクタをエンボステープ梱包したものである。
- 本品の形状及び寸法規定は JIS C 0806 (電子部品のテーピング (表面実装部品)) に準拠する。



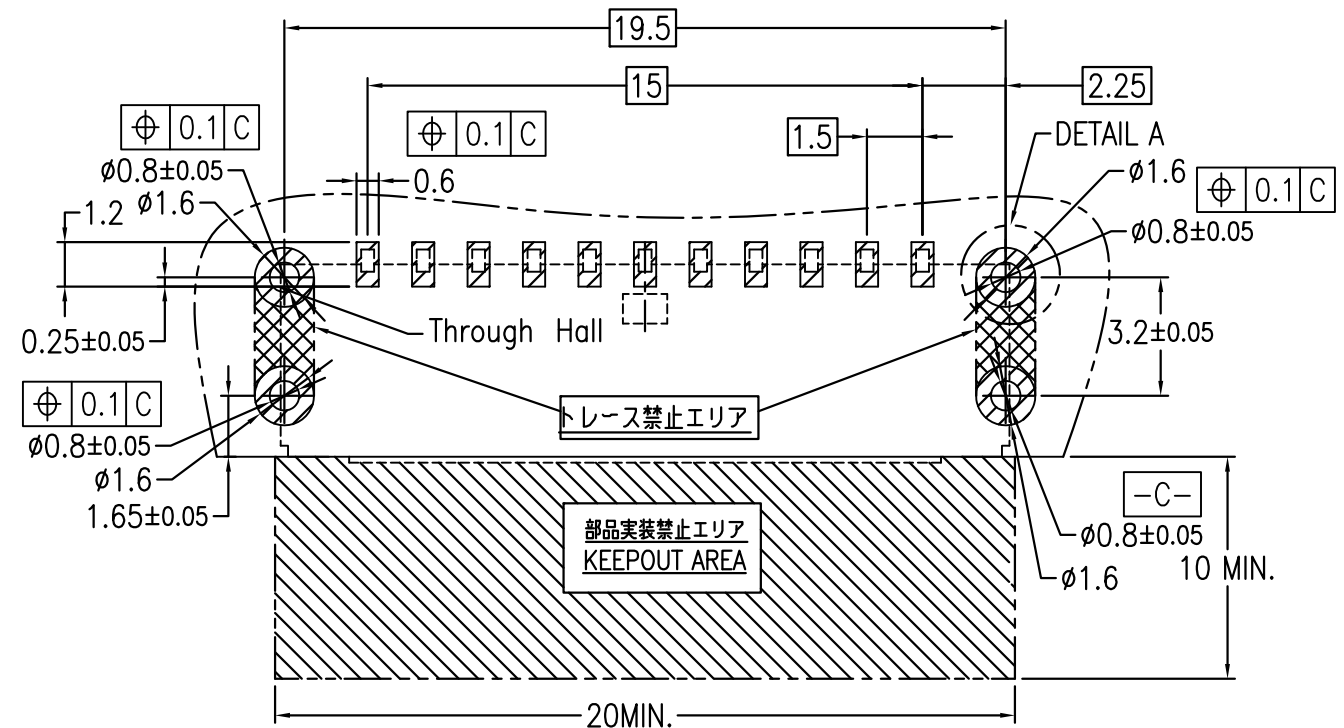
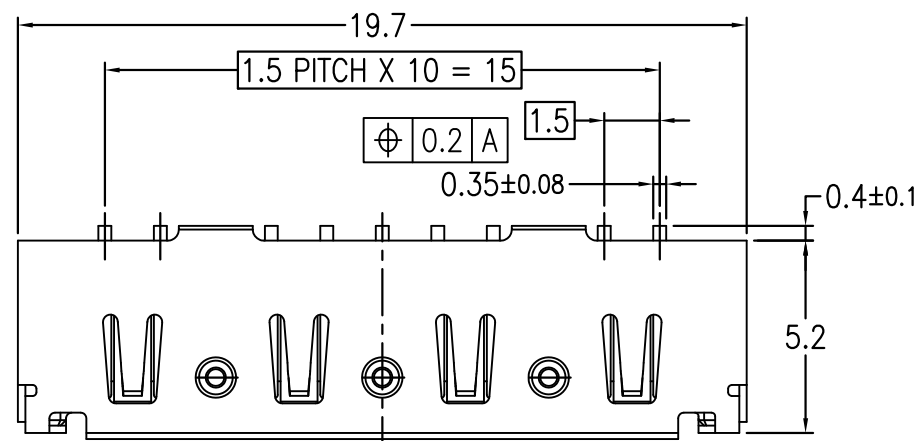
VIEW "A" (N.S.)  
矢視 "A" (N.S.)



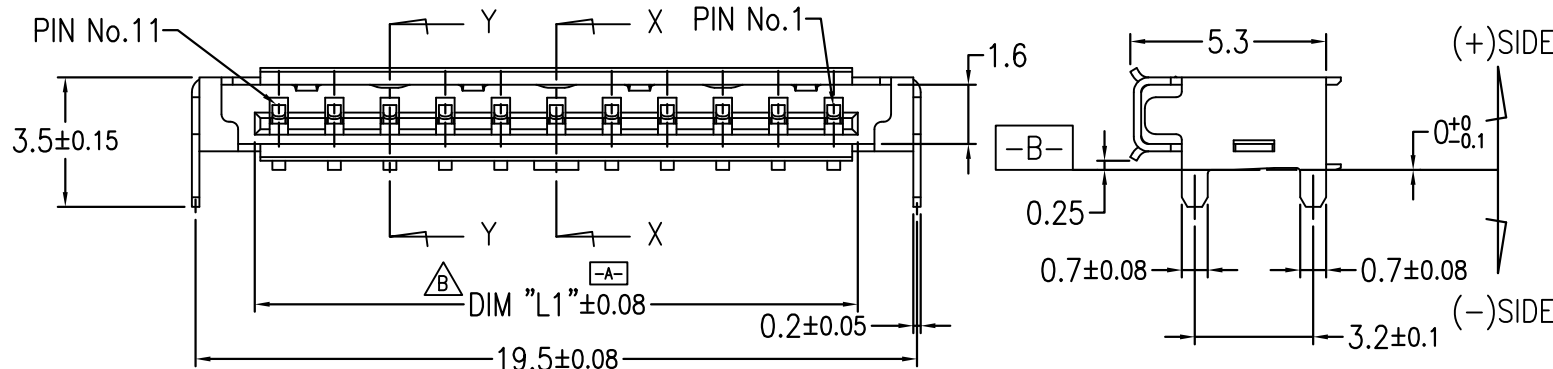
DETAIL "B" (1/1)  
"B"部詳細図 (1/1)

mat'l. code ---				surface ISO 1302 ✓		tolerance ISO 406 ISO 1101		projection MM		product family		CODE JP	
ltr description ecn no dr date				tolerances unless otherwise specified		angles linear		scale 1:5		title Micro Channel Connector Board Conn ASSY			
A	RELEASED	J05-0402	Y.K	6/27/'05			0.X ±0.3						
B	REVISED	J07-0184	Y.K	3/26/'07			0.XX ±0.3						
C	REVISED	ELX-J-011080	Y.K	2012-3-27	0°±2'		0.XXX ±0.3						
				dr		Y.KAMEDA		2012-3-27		dwg no		sheet 1 of 2 size	
				enr		Y.KAMEDA		2012-3-27		10042856		A3	
				chr		H.SUZUKI		2012-3-27		type		Product Customer Drawing	
				appd		M.KAJIURA		2012-3-27				Rev.	
sheet index		revision sheet		C C								C	
		1 2											

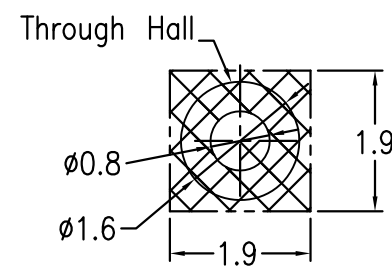
PRODUCT NO.	DIM "L1"	$\triangle B$
<del>10042856-4001</del>	<del>16.3</del>	$\triangle B \triangle C$
10042856-4001LF	16.4	$\triangle B$



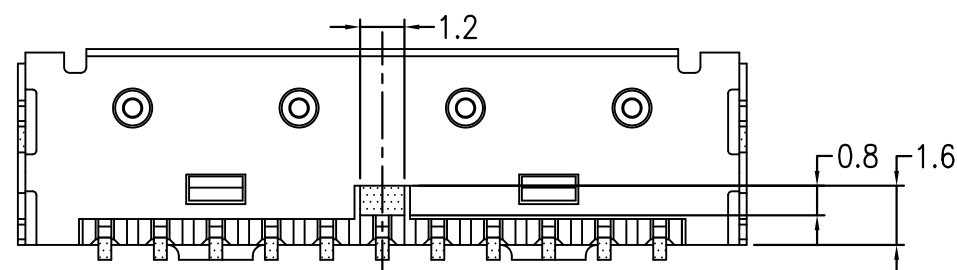
$\triangle C$  RECOMMENDED MOUNTING LAYOUT  
TOLERANCE UNLESS OTHERWISE:  $\pm 0.1$



- NOTE
- MATERIAL :  
HOUSING :HIGH TEMPERATURE THERMOPLASTIC,UL94V-0  
CONTACT :COPPER ALLOY(t=0.15)  
METAL SHELL :COPPER ALLOY(t=0.2)
  - FINISH :  
CONTACT :ALL OVER Ni 1.27 $\mu$ m MIN.  
Au FLASH  
METAL SHELL :ALL OVER Ni 1.27 $\mu$ m MIN.  
Sn PLATING 1.27 $\mu$ m MIN.
  - GENERAL TOLERANCE :  $\pm 0.3$
  - CO-PLANARITY : 0.1MAX
  - OTHER SPECIFICATIONS  
 $\triangle C$  PACKAGING SPEC : GS-14-2225  
 $\triangle C$  PRODUCT SPEC : GS-12-303



Detail A (Pin In Paste)  
Reference: Solder paste area  
t = 150 $\mu$ m



: P.C.B mount surface

mat'l. code ---		surface ISO 1302 <input checked="" type="checkbox"/>		tolerance ISO 406 ISO 1101		projection 		product family HPL533 SATA OTHER		CODE JP	
ltr		description		ecn no		dr		date		tolerances unless otherwise specified	
A		RELEASED		J05-0402		Y.K		6/27/'05		angles linear	
B		REVISED		J07-0184		Y.K		3/26/'07		0.X $\pm 0.3$	
C		REVISED		ELX-J-011080		Y.K		2012-3-27		0.XX $\pm 0.3$	
										0.XXX $\pm 0.3$	
				dr		Y.KAMEDA		2012-3-27		scale 5:1	
				enr		Y.KAMEDA		2012-3-27			
				chr		H.SUZUKI		2012-3-27		dwg no	
				appd		M.KAJIURA		2012-3-27		sheet 2 of 2	
sheet index		revision sheet								size	
										A3	
										type	
										Product Customer Drawing	
										Rev.	
										C	